

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

APPLE INC.,
Petitioner

v.

IMBERATEK, LLC,
Patent Owner

Case IPR2025-00582
Patent 9,107,324

PETITIONER'S UPDATED LIST OF EXHIBITS

LIST OF EXHIBITS

- APPLE-1001 U.S. Patent No. 9,107,324 (“the ’324 Patent”)
- APPLE-1002 U.S. Patent No. 9,107,324 File History
- APPLE-1003 Declaration of Vivek Subramanian
- APPLE-1004 Curriculum Vitae of Vivek Subramanian
- APPLE-1005 U.S. Patent Application Publication No. 2004/0168825 (“Sakamoto”)
- APPLE-1006 U.S. Patent No. 6,396,148 (“Eichelberger”)
- APPLE-1007 Green, T.A., “Gold electrodeposition for microelectronic, optoelectronic and microsystem applications.” *Gold Bull* 40, 105–114 (2007) (“Green”)
- APPLE-1008 Chang, Shou-Yi, et al. “Integrated electrochemical deposition of copper metallization for ultralarge-scale integrated circuits.” *Journal of The Electrochemical Society* 151.1 (2003) (“Chang”)
- APPLE-1009 Qi, Guojun, et al., “Zincating morphology of aluminum bond pad: its influence on quality of electroless nickel bumping.” *Thin Solid Films*, Volume 406, Issues 1–2 (2002)
- APPLE-1010 Arshad, M. et al., “The effects of zincation process on aluminum bond pad surfaces for electroless nickel immersion gold (ENIG) deposition,” *2004 IEEE International Conference on Semiconductor Electronics, Kuala Lumpur, Malaysia* (2004)
- APPLE-1011 Lee, Sung-Ki et al., “A study on the nucleation behavior of zinc particles on aluminum substrate,” *Advances in Electronic Materials and Packaging* (2001)

APPLE-1012 U.S. Patent Application Publication No. 2007/0126030
("Ito")

APPLE-1013 [Reserved]

APPLE-1014 International Patent Application Publication No.
2006/056643 ("Tuominen")

APPLE-1015 U.S. Patent Application Publication No. 2008/0032447
("Lee")

APPLE-1016 U.S. Patent No. 4,246,595 ("Noroyi")

APPLE-1017 Yung, W et al., "CO2 laser drilling of micro-via without
conformal mask in PCB manufacture." *Proceedings of the
1st Pacific International Conference on Laser Materials
Processing, Micro, Nano and Ultrafast Fabrication.*
PICALO (2004): 1st Pacific International Conference on
Laser Materials Processing, Micro, Nano and Ultrafast
Fabrication. Melbourne, Australia.

APPLE-1018 File history of U.S. Application No. 12/990,785

APPLE-1019 Hsu, S. (2015). Fluxless Tin Bonding Processes with
Intermetallic Study and Aluminum Circuit Board
Technology. *UC Irvine.*

APPLE-1020 Coombs, C. Printed Circuit Handbook (Sixth Edition),
McGraw-Hill Companies (2008).

APPLE-1021 Weste, N. and Esraghian, K., Principles of CMOS VLSI
Design, Addison-Wesley Publishing Company (1988).

APPLE-1022 Goh, W. et al., "The use of electroless copper seed in
electrochemical deposited copper interconnect," *Thin Solid
Films* 462–463, (2004): 275-278

- APPLE-1023 Kulkarni, A. K., and C. Lai. "New models for ohmic contacts to GaAs." *Thin Solid Films* 164 (1988): 435-439.
- APPLE-1024 Excerpt from Keller, H. and Erb, U., *Dictionary of Engineering Materials*, John Wiley & Sons, Hoboken, NJ (2004)
- APPLE-1025 Excerpt from Kaplan, S., *Wiley Electrical and Electronics Engineering Dictionary*, John Wiley & Sons, Hoboken, NJ (2004)
- APPLE-1026 Rossnagel, S, "Directional and preferential sputtering-based physical vapor deposition," *Thin Solid Films* 263 (1995): 1-12
- APPLE-1027 U.S. Patent No. 7,067,911
- APPLE-1028 Bauer, M. and Schneider, J., "Adhesives in the Electronics Industry," published in *Handbook of Adhesive Technology* (Second Edition), Marcel Dekker, New York, NY (2003)
- APPLE-1029 Declaration of June Ann Munford
- APPLE-1030 Apple Inc. Stipulation Letter

Respectfully submitted,

Dated: April 29, 2025

/Hyun Jin In/

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CERTIFICATE OF SERVICE

Pursuant to 37 CFR § 42.6(e), the undersigned certifies that on April 29, 2025, a complete and entire copy of this Petitioner's Updated List of Exhibits and its supporting exhibit were provided to the Patent Owner by serving the correspondence address of record as follows:

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